

**10/577173**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Wolfgang Hetzel et al.

Serial No.: Unknown  
(Priority Application No. DE 103 50 239.4)  
(International Application No. PCT/DE2004/002374)

**14720830 RECEIVED 26 APR 2006**

Filed: Herewith  
(Priority Date: October 27, 2003)  
(International Filing Date: October 25, 2004)

Docket No.: I431.156.101/FIN546PCT/US

Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING  
COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND  
METHOD FOR PRODUCING THE SAME

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**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

This Preliminary Amendment amends the Utility Patent Application filed herewith and should be used to calculate filing fees due. Prior to examination of the above-identified patent application, please amend as follows: